

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.26614	100.0	13.91631
			<b>Subtotal</b>	<b>0.26614</b>	<b>100</b>	<b>13.91631</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	0.45133	100.0	23.6
			<b>Subtotal</b>	<b>0.45133</b>	<b>100</b>	<b>23.6</b>
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.02391	5.0	1.25
	Pure metal	Silver (Ag)	7440-22-4	0.00717	1.5	0.375
	Pure metal	Lead (Pb)	7439-92-1	0.44703	93.5	23.375
			<b>Subtotal</b>	<b>0.47811</b>	<b>100</b>	<b>25</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00798	100.0	0.41749
			<b>Subtotal</b>	<b>0.00798</b>	<b>100</b>	<b>0.41749</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01899	0.03	0.993
	Copper alloy	Iron (Fe)	7439-89-6	0.0633	0.1	3.31
	Copper alloy	Copper (Cu)	7440-50-8	63.21933	99.87	3305.697
			<b>Subtotal</b>	<b>63.30162</b>	<b>100</b>	<b>3310</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.66935	100.0	35
			<b>Subtotal</b>	<b>0.66935</b>	<b>100</b>	<b>35</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.56715	4.5	81.945
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.48255	10.0	182.1
	Filler	Silica fused	60676-86-0	26.11909	75.0	1365.75
	Metal hydroxide	Metal hydroxide		3.48255	10.0	182.1
	Carbon Black	Carbon black	1333-86-4	0.17413	0.5	9.105
			<b>Subtotal</b>	<b>34.82547</b>	<b>100</b>	<b>1821</b>
			<b>Total</b>	<b>100</b>	<b>100</b>	<b>5228.9338</b>

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